PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT2935886

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
HAMZA YILMAZ	01/25/2013
MADHUR BOBDE	01/25/2013
HONG CHANG	01/25/2013
YEEHENG LEE	01/25/2013
DANIEL CALAFUT	01/25/2013
JONGOH KIM	01/07/2013
SIK LUI	01/25/2013
JOHN CHEN	01/25/2013

RECEIVING PARTY DATA

Name:	ALPHA AND OMEGA SEMICONDUCTOR INCORPORATED
Street Address:	475 OAKMEAD PKWY
City:	SUNNYVALE
State/Country:	CALIFORNIA
Postal Code:	94085

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	14329806

CORRESPONDENCE DATA

Fax Number: (510)668-0239

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 510-668-0965
Email: stephen@jdipatent.com
Correspondent Name: JOSHUA D. ISENBERG JDI PATENT
Address Line 1: 809 CORPORATE WAY
Address Line 4: FREMONT, CALIFORNIA 94539

ATTORNEY DOCKET NUMBER:	ANO-58/DIV
NAME OF SUBMITTER:	JOSHUA D. ISENBERG
SIGNATURE:	/Joshua D. Isenberg, REg. No. 41088/
DATE SIGNED:	07/11/2014

Total Attachments: 8
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Attorney Docket No: **ANO-058/US**

ASSIGNMENT

INVENTOR AND CITY

Whereas, I, **HAMZA YILMAZ** residing at
Saratoga, California, USA

have invented:

TITLE:

DEVICE STRUCTURE AND METHODS OF MAKING HIGH DENSITY MOSFETS FOR LOAD SWITCH AND DC-DC APPLICATIONS

DATE INVENTOR SIGNED THE DECLARATION

and executed a United States patent application therefor

on ____________, 2013. Said assignor hereby authorize and request their attorney, Joshua D. Isenberg, of 809 Corporate Way, Fremont, California, to insert here in parentheses (Application number 14/329,806, filed July 11, 2014) the filing date and application number of said application when known.

Whereas, **Alpha and Omega Semiconductor Incorporated,** a California Corporation, having its registered address at 475 Oakmead Pkwy, Sunnyvale, CA 94085, (hereinafter called **AOS**), desires to acquire the entire right, title and interest of said application and invention, and to any United States and foreign patents to be obtained therefore;

Now therefore for a valuable consideration, receipt whereof is hereby acknowledged, I, the above named, hereby sell, assign, and transfer to **AOS**, its successors and assigns, the entire right, title and interest in the said application and invention therein disclosed for the United States and foreign countries, and all rights of priority resulting from the filing said United States application, and I request the Commissioner of Patents to issue any Letters Patent granted upon the invention set forth in said application to **AOS** its successors and assigns; and I hereby agree that **AOS** may apply for foreign Letters Patent on said invention and I will execute all papers necessary in connection with the United States and foreign applications when called upon to do so by

CITY AND Signed and Sealed at Sunnyvale

DATE on Jan. 25, 2013

Hamza Yilmaz

ASSIGNMENT

INVENTOR AND CITY

Whereas, I, **MADHUR BOBDE** residing at
Sunnyvale, California, USA

have invented:

TITLE:

DEVICE STRUCTURE AND METHODS OF MAKING HIGH DENSITY MOSFETS FOR LOAD SWITCH AND DC-DC APPLICATIONS

DATE INVENTOR SIGNED THE DECLARATION

and executed a United States patent application therefor on ______________, 2013 . Said assignor hereby authorize and request their attorney, Joshua D. Isenberg, of 809 Corporate Way, Fremont, California, to insert here in parentheses (Application number 14/329,806, filed July 11, 2014) the filing date and application number of said application when known.

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CITY AND

Signed and Sealed at Sunnyvale, CA

DATE

on Jan 25th, 2013

____
Madhur Bobde

Attorney Docket No: **ANO-058/US**

ASSIGNMENT

INVENTOR AND CITY

Whereas, I, **HONG CHANG** residing at
Saratoga, California, USA

have invented:

TITLE:

DEVICE STRUCTURE AND METHODS OF MAKING HIGH DENSITY MOSFETS FOR LOAD SWITCH AND DC-DC APPLICATIONS

DATE INVENTOR SIGNED THE DECLARATION

and executed a United States patent application therefor

on ______________, 2013. Said assignor hereby authorize and request their attorney, Joshua D. Isenberg, of 809 Corporate Way, Fremont, California, to insert here in parentheses (Application number 14/329,806, filed July 11, 2014) the filing date and application number of said application when known.

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CITY AND Signed and Sealed at Sunnyvale, CA

DATE on Jan 25th, 2013

Hong Chang

Attorney Docket No: **ANO-058/US**

ASSIGNMENT

INVENTOR AND CITY Whereas, I, **YEEHENG LEE** residing at
San Jose, California, USA

have invented:

TITLE: **DEVICE STRUCTURE AND METHODS OF MAKING HIGH DENSITY MOSFETS FOR LOAD SWITCH AND DC-DC APPLICATIONS**

DATE INVENTOR SIGNED THE DECLARATION and executed a United States patent application therefor

on ______________, 2013. Said assignor hereby authorize and request their attorney, Joshua D. Isenberg, of 809 Corporate Way, Fremont, California, to insert here in parentheses (Application number `14/329,806`, filed `July 11, 2014`) the filing date and application number of said application when known.

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CITY AND Signed and Sealed at Sunnyvale, CA

DATE on Jan 8th, 2013

Yeeheng Lee

Attorney Docket No: **ANO-058/US**

ASSIGNMENT

INVENTOR AND CITY

Whereas, I, **DANIEL CALAFUT** residing at
San Jose, California, USA

have invented:

TITLE:

DEVICE STRUCTURE AND METHODS OF MAKING HIGH DENSITY MOSFETS FOR LOAD SWITCH AND DC-DC APPLICATIONS

DATE INVENTOR SIGNED THE DECLARATION

and executed a United States patent application therefor

on ______________, 2013 Said assignor hereby authorize and request their attorney, Joshua D. Isenberg, of 809 Corporate Way, Fremont, California, to insert here in parentheses (Application number 14/329,806, filed July 11, 2014) the filing date and application number of said application when known.

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Now therefore for a valuable consideration, receipt whereof is hereby acknowledged, I, the above named, hereby sell, assign, and transfer to **AOS**, its successors and assigns, the entire right, title and interest in the said application and invention therein disclosed for the United States and foreign countries, and all rights of priority resulting from the filing said United States application, and I request the Commissioner of Patents to issue any Letters Patent granted upon the invention set forth in said application to **AOS** its successors and assigns; and I hereby agree that **AOS** may apply for foreign Letters Patent on said invention and I will execute all papers necessary in connection with the United States and foreign applications when called upon to do so by

CITY AND Signed and Sealed at Sunnyvale, CA

DATE on Jan 25th, 2013

Daniel Calafut

Attorney Docket No: **ANO-058/US**

ASSIGNMENT

INVENTOR AND CITY Whereas, I, **JONGOH KIM** residing at
Portland, Oregon, USA

have invented:

TITLE: **DEVICE STRUCTURE AND METHODS OF MAKING HIGH DENSITY MOSFETS FOR LOAD SWITCH AND DC-DC APPLICATIONS**

DATE INVENTOR SIGNED THE DECLARATION and executed a United States patent application therefor on ______________, 2012. Said assignor hereby authorize and request their attorney, Joshua D. Isenberg, of 809 Corporate Way, Fremont, California, to insert here in parentheses (Application number 14/329,806 , filed July 11, 2014) the filing date and application number of said application when known.

Whereas, **Alpha and Omega Semiconductor Incorporated, a** California Corporation, having its registered address at 475 Oakmead Pkwy, Sunnyvale, CA 94085, (hereinafter called AOS), desires to acquire the entire right, title and interest of said application and invention, and to any United States and foreign patents to be obtained therefore;

Now therefore for a valuable consideration, receipt whereof is hereby acknowledged, I, the above named, hereby sell, assign, and transfer to AOS, its successors and assigns, the entire right, title and interest in the said application and invention therein disclosed for the United States and foreign countries, and all rights of priority resulting from the filing said United States application, and I request the Commissioner of Patents to issue any Letters Patent granted upon the invention set forth in said application to AOS its successors and assigns; and I hereby agree that AOS may apply for foreign Letters Patent on said invention and I will execute all papers necessary in connection with the United States and foreign applications when called upon to do so by

CITY AND Signed and Sealed at Portland, OR

DATE on 6/7/2013, ~~2012~~

Jongoh Kim

Attorney Docket No: **ANO-058/US**

ASSIGNMENT

INVENTOR AND CITY

Whereas, I, **SIK LUI** residing at
Sunnyvale, California, USA

have invented:

TITLE:

DEVICE STRUCTURE AND METHODS OF MAKING HIGH DENSITY MOSFETS FOR LOAD SWITCH AND DC-DC APPLICATIONS

DATE INVENTOR SIGNED THE DECLARATION

and executed a United States patent application therefor

on ______________, 2013. Said assignor hereby authorize and request their attorney, Joshua D. Isenberg, of 809 Corporate Way, Fremont, California, to insert here in parentheses (Application number 14/329,806, filed July 11, 2014) the filing date and application number of said application when known.

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CITY AND

Signed and Sealed at Sunnyvale

DATE

on Jan. 25, 2013

Sik Lui

Sik Lui

Attorney Docket No: **ANO-058/US**

ASSIGNMENT

INVENTOR AND CITY

Whereas, I, **JOHN CHEN** residing at
Palo Alto, California, USA

have invented:

TITLE:

DEVICE STRUCTURE AND METHODS OF MAKING HIGH DENSITY MOSFETS FOR LOAD SWITCH AND DC-DC APPLICATIONS

DATE INVENTOR SIGNED THE DECLARATION

and executed a United States patent application therefor

on ______________, 2013 . Said assignor hereby authorize and request their attorney, Joshua D. Isenberg, of 809 Corporate Way, Fremont, California, to insert here in parentheses (Application number 14/329,806, filed July 11, 2014) the filing date and application number of said application when known.

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CITY AND

Signed and Sealed at Sunnyvale, CA

DATE

on Jan 25th, 2013

John Chen